

Amendments to the Specification

Please amend the paragraph beginning on page 6, line 27 as follows:

FIGS. 1 through 3 ~~schematic~~ schematically show in cross section a substrate processing apparatus according to an embodiment of the present invention for processing a substrate with a chemical liquid, cleaning the processed substrate, and spin-drying the cleaned substrate with a single processing facility. As shown in FIGS. 1 through 3, the substrate processing apparatus has a substrate holder 16 for detachably holding a substrate W. The substrate holder 16 comprises a disk-shaped substrate stage 12 coupled to the upper end of a main shaft 10 that is rotatable about its own axis, and a plurality of substrate holding chucks 14 mounted in upstanding posture on the outer circumferential edge of an upper surface of the substrate stage 12 and angularly ~~spaced~~ spaced at a predetermined interval or pitch along the outer circumferential edge. The substrate holder 16 is arranged to rotate in unison with the substrate W while holding the substrate W.

Please amend the paragraph beginning on page 11, line 24 as follows:

A fluid passage 46 is defined between the inner circumferential surface of the hollow main shaft 10 and the outer circumferential surface of the fixed shaft 32. The fluid passage 46 is connected to an inactive gas supply line 48 which supplies an inactive gas, such as an N₂ gas or the like. The inactive gas is ~~blew~~ blown through the fluid passage 46 toward the reverse side of the substrate W held by substrate holder 16 to prevent a negative pressure (a pressure lower than the atmospheric pressure) from being developed in the space between the substrate W that is being rotated at a high speed and the substrate stage 12.